CLAIMS

1. A semiconductor device comprising:

a substrate having pads;

a first semiconductor chip mounted on said substrate and having pads;

a plate member arranged on said first semiconductor chip and having an end at an inward position of said first semiconductor chip from the pads;

a second semiconductor chip arranged on said plate member and having pads;

a structure electrically connecting said pads of said first semiconductor chip and said pads of said second semiconductor chip to said pads of said substrate; and

a seal member sealing said first semiconductor chip and said second semiconductor chip.

2. A semiconductor device according to claim 1, wherein said structure electrically connecting said pads of said first semiconductor chip and said pads of said second semiconductor chip to said pads of said substrate comprises wires.

3. A semiconductor device according to claim 1, wherein said plate member has a side surface exposed to the outside said seal member through a side surface thereof.

4. A semiconductor device according to claim 1, wherein said plate member comprises a plurality of laminated layers.

5. A semiconductor device according to claim 1, wherein said plate member includes pads and said structure electrically connecting said pads of said first semiconductor chip and said pads of said second semiconductor chip to said pads of said substrate includes members electrically connecting at least one of said pads of said second semiconductor chip and said pads of said second semiconductor chip to said pads of said plate member and members electrically connecting said

pads of said plate member to said pads of said substrate.

6. A semiconductor device according to claim 1, wherein said plate member has a first portion covered by said first and second semiconductor chips, and a second portion protruding from said first and second semiconductor chips, said second portion having a side surface flush with a side surface of the seal member.